## **SEMICAPS 3000**

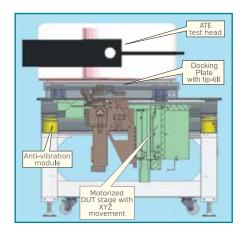
## DIRECT TESTER-DOCKED SYSTEM



- For backside analysis of wafers, wafer parts and packaged devices. Able to dock with all ATE platforms
- Easily moved from Tester to Tester
- Custom docking for all ATE platforms
- High resolution stage with 0.5 µm repeatability
- Centric and Aplanatic Refractive Solid Immersion Lens (RSIL) option
- CAD interface option
- Compatible with thermal management solutions
- Techniques include a combination of :
  - Laser Timing Probe (LTP)
  - Scanning Optical Microscopy (SOM) with best sensitivity static: TIVA, OBIRCH

dynamic: LADA, SDL

- Photon Emission Microscopy (PEM) with various options for the InGaAs or Si-CCD camera
- Thermal Microscopy (THM) with InSb camera



ATE-Docked

